L Number	Hits	Search Text	DB	Time stamp
1	4693	(((chip near sized near package) (chip	USPAT;	2003/01/24 09:50
		near scale near package) csp)) not	US-PGPUB;	2000/01/24 09:50
		(flipchip (flip near chip))	EPO; JPO;	
			DERWENT	
2	5816	((chip near sized near package) (chip near	USPAT;	2003/01/24 09:50
1		scale\$1 near package) csp)	US-PGPUB;	
			EPO; JPO;	
3	387	(((chip near sized near package) (chip	DERWENT	
	507	near scale\$1 near package) csp)) and	USPAT;	2003/01/24 09:51
		(dissipat\$3 (heat near sink)) and (hole	US-PGPUB;	
		opening)	EPO; JPO; DERWENT	
4	5816	(((chip near sized near package) (chip	USPAT;	2003/01/24 09:52
i		near scale\$1 near package) csp))(((chip	US-PGPUB;	2003/01/24 09:52
		near sized near package) (chip near scale	EPO; JPO;	
		near package) csp)) not (flipchip (flip	DERWENT	
		near chip))) (((chip near sized near		
		package) (chip near scale\$1 near package)		
		csp)) and (dissipat\$3 (heat near sink)) and (hole opening via)		ļ
5	5816	((((chip near sized near package) (chip	HODE	
		near scale near package) csp)) not	USPAT; US-PGPUB;	2003/01/24 09:52
		(flipchip (flip near chip))) (((chip near	EPO; JPO;	
		sized near package) (chip near scales1	DERWENT	
		near package) csp))		
6	256	(((((chip near sized near package) (chip	USPAT;	2003/01/24 09:54
		near scale near package) csp)) not	US-PGPUB;	, , , , , , , , , , , , , , , , , , , ,
		(flipchip (flip near chip))) (((chip near	EPO; JPO;	
		sized near package) (chip near scale\$1 near package) csp))) and (heat near1	DERWENT	
	j	dissipat\$3) and (via vias hole opening)		
7	149	(((((chip near sized near package) (chip	HODAm.	0000 (01 (01)
		near scale near package) csp)) not	USPAT; US-PGPUB;	2003/01/24 09:59
		(flipchip (flip near chip))) (((chip near	EPO; JPO;	
		sized near package) (chip near scale\$1	DERWENT	
		near package) csp))) and (heat near)		
		dissipat\$3) and (via vias hole opening)		
		and (electrode (bond\$3 adi pad)) and		
		((encapsulant encapsulating encapsulated		
		encapsulation) sealing resin)		